

| PROJECT | | | PLOTTER INFORMATION | | | | |
|-------------------------------|-----|-----------------------|---|--|-----------------------|-------------------|--|
| Design name | PCB | AMIS_REV2_305XX_V2 | Units | | Imperial | | |
| Design File name | PCB | 14162 | Gerber type | | RS274-X | | |
| Circuit number | SCM | 0000-000-14162 | Data type | | Absolute X/Y-positive | | |
| Reference | | Patrick van den Hurk | Output code | | ASCII | | |
| Date | | 17-07-2009 | Resolution | | 1/10000 inch | | |
| Size | | 32.00x44.00mm | | | | | |
| Size tolerance | | +0.10 -0.20mm | NC | | | | |
| Total layers | | 2 | Size | | 32.00x44.00mm | | |
| Powerplanes | | No | Units | | Imperial | | |
| Burried vias | | No | Machine | | Excellon | | |
| Blind vias | | No | Output code | | ASCII | | |
| SMD technologie | | Yes, both sides | | | | | |
| Solder resists | | Yes, both sides | Hole Tolerances | | | | |
| Silkscreen | | Yes, both sides | Plated holes | | >0.4 <1.5mm | + 0.1mm / - 0.0mm | |
| Remarks | | Non manufacturer code | | | >1.5mm | +/- 0.1mm | |
| | | | Non plated holes | | >0.5<1.5mm | +/- 0.05mm | |
| | | | | | >1.5mm | +/-0.1mm | |
| MATERIALS | | | Finishing holes | | | | |
| Basic material | | FR4 | Finishing plated through holes: | | | | |
| Finishing Cu layers | | 35uM Finish | | | | | |
| Finishing Cu inner layers | | Not of application | | | | | |
| Board thickness | | 1.6 mm | | | | | |
| Board finish | | HAL | | | | | |
| | | | MILL BOARDOUTLINES AND INTERNALCUTOUTS | | | | |
| | | | The position from the boardoutline and boardcutouts represent the exact centerline to complete the dimensions (use 14162_MD.pdf as graphic presentation) The milltool has to be positioned near the centerline with a offset half the diameter from the tool. | | | | |
| | | | | | | | |
| LAYERBUILDUP SHORTFORM | | | Use for the internal plated millings : 14162_PC.gbr | | | | |
| Top of board | | | Use for the internal non plated millings : 14162_NPC.gbr | | | | |
| TSI | | Top silkscreen | | | | | |
| TS | | Top solder resist | | | | | |
| L1 | | Top elec signals | SCORE BOARDOUTLINES | | | | |
| L2 | | Bottom elec signals | The position from the boardoutline represent the exact centerline to complete the dimensions (use 14162_MD.pdf as graphic presentation) | | | | |
| BS | | Bottom solder resist | The score tool has to be positioned at the centerline. | | | | |
| BSI | | Bottom silkscreen | | | | | |
| Bottom of board | | | | | | | |
| | | | | | | | |

| | | | | | | | | |
|--|--|-------------------------|--|--|--|--|--|--|
| | | | | | | | | |
| FILES INCLUDED | | | | | | | | |
| Top Slikscreen | | 14162_TSI.gbr | | | | | | |
| Top Solder Resist | | 14162_TS.gbr | | | | | | |
| Top Elec | | 14162_L1.gbr | | | | | | |
| Bottom Elec | | 14162_L2.gbr | | | | | | |
| Bottom Solder Resist | | 14162_BS.gbr | | | | | | |
| Bottom Slikscreen | | 14162_BSI.gbr | | | | | | |
| | | | | | | | | |
| Mechanical Drawing | | 14162_MD.pdf | | | | | | |
| | | | | | | | | |
| Plated Holes (excellon) | | 14162_PT.exl | | | | | | |
| Plated Holes (toollist) | | 14162_PT.tl | | | | | | |
| | | | | | | | | |
| Non Plated Holes (excellon) | | 14162_NP.exl | | | | | | |
| Non Plated Holes (toollist) | | 14162_NP.tl | | | | | | |